

*The Organizing Committee of 2021 7th International Workshop  
on Low Temperature Bonding for 3D Integration (LTB-3D)*

*October 5-11, 2021, Online*

*delivers*

*Best Student Presentation Award*

*to*

*R. Kagawa<sup>1</sup>, K. Kawamura<sup>2</sup>, Y. Sakaida<sup>2</sup>, S. Ouchi<sup>2</sup>, H. Uratani<sup>2</sup>, Y. Shimizu<sup>3</sup>,  
Y. Ohno<sup>4</sup>, Y. Nagai<sup>3</sup>, N. Shigekawa<sup>1</sup>, J. Liang<sup>1</sup>;*

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*Fabrication of GaN/SiC/diamond structure  
for efficient thermal management of power device*



*Naoteru Shigekawa*

*Naoteru Shigekawa, The Chair of LTB3D 2021*